

# IC Package Report

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- This report analyzes the market size trends and forecasts from 2022 to 2034 by package type and region for various types of ICs.
- ICs are classified into 17 types, with each IC analyzed by 14 package types and across 8 regions.

Japan Marketing Survey Co., Ltd.

2-24-12 Higashi-Nihonbashi, Chuo City, Tokyo 103-0004 Japan

E-mail: [info@jms21.co.jp](mailto:info@jms21.co.jp) | <https://www.jms21.co.jp>

# Outline of this research report

## 1. Purpose

The purpose of this report is to offer an in-depth analysis of the IC packaging market trends, providing essential data to support strategic planning in this field.

## 2. Research period

From August to December 2025

## 3. Research Method

Information gathering: Direct or indirect survey, secondary research

## 4. Object of the research

Items		Description
ICs	Analog ICs	General purpose/Application specific
	Memory ICs	DRAM/NAND Flash/NOR Flash/Others
	Logic ICs	MPU/GPU/ASIC&FPGA/Mobile AP/MCU/Special Purpose Logic: Consumer, Computer, Wireless Comms, Network, Automobile/Display Driver/Others
Package types	Lead frame	PIH: SIP/DIP, SMT: SOP/TSOP, CSP: SON/QFN
	Substrates	CSP: PCSP/FCCSP/SiP, BGA: PBGA/FCBGA/2.xD PKG, COF/TCP
	Substrate-less	Fan in WLP/Fan out WLP/PLP/Bare chip
Region		China/Taiwan/Korea/Japan/ROA (Rest of Asia)/NA (North America)/Europa/ROW (Rest of World)

# Sample Report Format-1

## Forecast by Package Type for \*\*\*\*\* IC

		2022	2023	2024	2025	2026	2027	2028	2029	2030	2032	2034	
Lead Frame	PIH: SIP/DIP	1,670	1,250	1,140	1,200	1,100	1,070	1,050	1,020	1,000	950	900	
	SMT: SOP/QFP	14,820	9,530	9,500	11,700	11,800	11,830	12,000	12,100	12,200	12,300	12,450	
	CSP: SON/QFN	10,090	7,200	7,100	9,050	9,100	9,180	9,300	9,460	9,640	9,920	10,440	
	Sub total	26,580	17,980	17,740	21,950	22,000	22,080	22,350	22,580	22,840	23,170	23,790	
Substrates	CSP	PCSP	330	220	200	210	220	220	230	230	240	250	260
		FCCSP	0	0	0	0	0	0	0	0	0	0	0
		SiP	0	0	0	0	0	0	0	0	0	0	0
		S-total	330	220	200	210	220	220	230	230	240	250	260
	BGA	PBGA	0	0	0	0	0	0	0	0	0	0	0
		FCBGA	0	0	0	0	0	0	0	0	0	0	0
		2.x D	0	0	0	0	0	0	0	0	0	0	0
		S-total	0	0	0	0	0	0	0	0	0	0	0
	COF/TCP	330	220	200	210	220	220	230	230	240	250	260	
	Sub total	880	800	810	830	860	900	940	1,000	1,120	1,170	1,230	
Substrate-less	FI-WLP	0	0	0	0	0	0	0	0	0	0	0	
	FO-WLP	0	0	0	0	0	0	0	0	0	0	0	
	FO-PLP	0	0	0	0	0	0	0	0	0	0	0	
	Bare Chip	170	100	110	140	150	180	190	200	220	240	250	
	Sub total	1,050	900	920	970	1,010	1,080	1,130	1,200	1,340	1,410	1,480	
Total	27,960	19,100	18,860	23,130	23,230	23,380	23,710	24,010	24,420	24,830	25,530		

Million pieces

# Sample Report Format-2

## Forecast of Regional IC Packaging Volumes by \*\*\*\* IC

	2022	2023	2024	2025	2026	2027	2028	2029	2030	2032	2034
China	13,870	8,900	8,740	10,540	10,610	10,770	11,140	11,350	11,540	11,700	12,000
Taiwan	2,040	1,470	1,450	1,600	1,490	1,400	1,230	1,160	1,100	1,050	1,000
Korea	890	640	630	650	630	620	560	530	500	470	440
Japan	1,710	1,330	1,040	1,100	1,020	950	870	800	750	700	660
ROA	7,980	5,560	5,930	8,110	8,340	8,490	8,740	8,980	9,310	9,620	10,000
NA	620	510	450	460	450	440	430	420	410	400	390
EU	490	400	360	380	370	360	350	330	310	290	270
ROW	360	290	260	290	320	350	390	440	500	600	770
Total	27,960	19,100	18,860	23,130	23,230	23,380	23,710	24,010	24,420	24,830	25,530

(Million PCS)

# Sample Report Format-3

## Market Size Forecast by DRAM Types

		2022	2023	2024	2025	2026	2027	2028	2029	2030	2032	2034
DDR DRAM	Vol.	17,330										
	Val.	58,880										
	ASP	3.4										
GDDR DRAM	Vol.	1,430										
	Val.	8,120										
	ASP	5.7										
LPDDR DRAM	Vol.	950										
	Val.	9,040										
	ASP	9.5										
HBM	Vol.	10										
	Val.	1,960										
	ASP	196.0										
Total	Vol.	19,720										
	Val.	78,000										
	ASP	4.0										

Vol.: MPCS, Val.: MUSD, ASP: USD/PCS

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Depending on the type of business other than manufacturers or trading companies, above these prices may not apply, or this publication may not be available.

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Date:    /    /

## **Report Title: IC Package Report**

Please check  type of contract →  Corporate Contract /  Global Contract

[Accepting the conditions of the type of contract \(previous page\)](#)

Corporate Name: \_\_\_\_\_.

Applicant's Name: \_\_\_\_\_.

Applicant's Department: \_\_\_\_\_.

Corporate Address: \_\_\_\_\_.

Phone: \_\_\_\_\_ Email: \_\_\_\_\_.

## Credit Card Information:

Card Type: Visa / Master / AMEX      Card Number : \_\_\_\_\_.

Expiration date:      /      Name on the card: \_\_\_\_\_.

Your request:

# Application Form (for Wire Transfer)



Date:    /    /

## Report Title: IC Package Report

Please check  type of contract →  Corporate Contract /  Global Contract

[Accepting the conditions of the type of contract \(previous page\)](#)

Corporate Name: \_\_\_\_\_.

Applicant's Name: \_\_\_\_\_.

Applicant's Department: \_\_\_\_\_.

Corporate Address: \_\_\_\_\_.

Phone: \_\_\_\_\_ Email: \_\_\_\_\_.

Please transfer the payment to the following:

\*Bank : MIZUHO BANK (Swift code: MHCBJPJT)  
\*Branch: Kobunacho Branch (Phone:+81-3-3661-3111), [Branch code: 105]  
\*Branch address: 8-1 Nihonbashi-Kobunacho, Chuo City, Tokyo 103-0024 Japan  
\*Account Number: 1653912 \*Account Name: Japan Marketing Survey Co., Ltd.

Your request: